## Nots International Symposium on Networks-on-Chip

## Call for Papers 10<sup>th</sup> IEEE/ACM International Symposium on Networks-on-Chip August 31 – September 2, 2016

Nara, Japan

The International Symposium on Networks-on-Chip (NOCS) is the premier event dedicated to interdisciplinary research on on-chip, chip-scale, and multichip package scale communication technology, architecture, design methods, applications and systems. NOCS brings together scientists and engineers working on NoC innovations and applications from inter-related research communities, including computer architecture, networking, circuits and systems, packaging, embedded systems, and design automation. Topics of interest include, but are not limited to:

NoC Architecture and Implementation	NoC Application
<ul> <li>Network architecture (topology, routing, arbitration)</li> </ul>	<ul> <li>Mapping of applications onto NoCs</li> </ul>
<ul> <li>NoC Quality of Service</li> </ul>	<ul> <li>NoC case studies, application-specific NoC design</li> </ul>
<ul> <li>Timing, synchronous/asynchronous communication</li> </ul>	<ul> <li>NoCs for FPGAs, structured ASICs, CMPs and MPSoCs</li> </ul>
<ul> <li>NoC reliability issues</li> </ul>	<ul> <li>NoC designs for heterogeneous systems, fused CPU-GPU</li> </ul>
<ul> <li>Network interface issues</li> </ul>	architectures, etc
<ul> <li>NoC design methodologies and tools</li> </ul>	<ul> <li>Scalable modeling of NoCs</li> </ul>
<ul> <li>Signaling &amp; circuit design for NoC links</li> </ul>	
	NoC at the Un-Core and System-level
NoC Analysis and Verification	<ul> <li>Design of memory subsystem (un-core) including memory</li> </ul>
<ul> <li>Power, energy &amp; thermal issues (at the NoC, un-core</li> </ul>	controllers, caches, cache coherence protocols & NoCs
and/or system-level)	<ul> <li>NoC support for memory and cache access</li> </ul>
<ul> <li>Benchmarking &amp; experience with NoC-based</li> </ul>	· OS support for NoCs
hardware	<ul> <li>Programming models including shared memory, message</li> </ul>
<ul> <li>Modeling, simulation, and synthesis of NoCs</li> </ul>	passing and novel programming models
<ul> <li>Verification, debug &amp; test of NoCs</li> </ul>	<ul> <li>Issues related to large-scale systems (datacenters,</li> </ul>
<ul> <li>Metrics and benchmarks for NoCs</li> </ul>	supercomputers) with NoC-based systems as building blocks
Novel NoC Technologies	On-Chip Communication Optimization
<ul> <li>New physical interconnect technologies, e.g., carbon</li> </ul>	<ul> <li>Communication efficient algorithms</li> </ul>
nanotubes, wireless NoCs, through-silicon, etc.	· Multi/many-core communication workload characterization
<ul> <li>NoCs for 3D and 2.5D packages</li> </ul>	& evaluation
<ul> <li>Package-specific NoC design</li> </ul>	<ul> <li>Energy efficient NoCs and energy minimization</li> </ul>
<ul> <li>Optical, RF, &amp; emerging technologies for on-chip/in-</li> </ul>	
package interconnects	

Electronic paper submission requires a full paper, up to 8 double-column IEEE format pages, including figures and references. The program committee in a double-blind review process will evaluate papers based on scientific merit, innovation, relevance, and presentation. *Submitted papers must describe original work that has not been published before or is under review by another conference or journal at the same time*. Each submission will be checked for any significant similarity to previously published works or for simultaneous submission to other archival venues, and such papers will be rejected. Proposals for special sessions, tutorials, and demos are invited. Paper submissions and demo proposals by industry researchers or engineers to share their experiences and perspectives are also welcome.

Please see the detailed submission instructions for paper submissions, special session, tutorial, and demo proposals at the submission page. Further information is available via:

## http://www.arc.ics.keio.ac.jp/nocs16

Important Dates

Abstract registration deadline	February, 5 <sup>th</sup> , 2	2016	Notification of acceptance	April 8 <sup>th</sup> , 2016
Full paper submission deadline	February 12 <sup>th</sup> ,	2016	Final version due	May 18 <sup>th</sup> , 2016
General Co-Chairs:		Techr	ical Program Co-Chairs:	
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